

Case No.: AMKOR-007C

Patent Appln.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Thomas P. Glenn

Serial No.: 09/615,107

Filed: 07/13/2000

For: PLASTIC INTEGRATED  
CIRCUIT PACKAGE AND  
METHOD AND LEAD FRAME  
FOR MAKING THE PACKAGE

Group No.: 2831

Examiner: C. Oliva

AUTHORIZATION LETTER

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON D.C. 20231

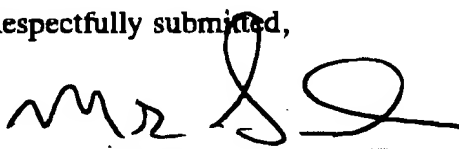
Dear Sir/Madam:

Please accept this letter as formal authorization to debit Deposit Account No. 19-4330 for the amount of \$520.00 to satisfy the third-month extension fee for the subject case.

Respectfully submitted,

Date: 2/28/02

By:



Mark B. Garred

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